

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-11 (canceled).

Claim 12 (currently amended): A high-frequency module for transmitting and receiving transmission-reception signals of communication systems of at least three kinds from an antenna, the signals to be inputted and outputted from particular input-output portions, respectively, the high-frequency module comprising:

an FET switch including an antenna input-output portion to be connected to the antenna and at least three signal input-output portions whose connection to the antenna input-output portion is switched in accordance with control signals to be inputted, the FET being constituted such that the transmission signals of communication systems of three kinds are inputted from different signal input-output portions and such that reception signals of at least two communication systems are outputted from the same signal input-output portion; and

a diplexer connected to the signal input-output portion of the FET switch, from which reception signals of at least two communication systems are outputted, the diplexer being arranged to separate the reception signals of the at least two communication systems; wherein

the high-frequency module is a high-frequency module arranged to transmit and receive transmission-reception signals of first, second, third, and fourth communication systems from the antenna, and the FET switch includes first, second, third, and fourth signal input-output portions and is constituted such that transmission signals of the first communication system and the second communication system are inputted to the first signal input-output portion, such that transmission signals of the third communication system and the fourth communication system are inputted to the second signal input-output portion, such that reception signals of the first communication system and the

fourth communication system are outputted from the third signal input-output portion, and such that reception signals of the second communication system and the third communication system are outputted from the fourth signal input-output portion; and
a first diplexer connected to the third signal input-output portion and arranged to separate a reception signal of the first communication system and a reception signal of the fourth communication system and a second diplexer connected to the fourth signal input-output portion and arranged to separate a reception signal of the second communication system and a reception signal of the third communication system are provided.

Claims 13 and 14 (canceled).

Claim 15 (currently amended): ~~A high-frequency module as claimed in claim 12,~~
A high-frequency module for transmitting and receiving transmission-reception signals of communication systems of at least three kinds from an antenna, the signals to be inputted and outputted from particular input-output portions, respectively, the high-frequency module comprising:

an FET switch including an antenna input-output portion to be connected to the antenna and at least three signal input-output portions whose connection to the antenna input-output portion is switched in accordance with control signals to be inputted, the FET being constituted such that the transmission signals of communication systems of three kinds are inputted from different signal input-output portions and such that reception signals of at least two communication systems are outputted from the same signal input-output portion; and

a diplexer connected to the signal input-output portion of the FET switch, from which reception signals of at least two communication systems are outputted, the diplexer being arranged to separate the reception signals of the at least two communication systems; wherein

the high-frequency module is a high-frequency module arranged to transmit and receive transmission-reception signals of first, second, third, and fourth communication

systems from the antenna, and the FET switch includes first, second, third, and fourth signal input-output portions and is constituted such that a transmission signal of the first communication system and a reception signal of the second communication system are inputted to the first signal input-output portion, such that transmission signals of the second communication system and the third communication system are inputted to the second signal input-output portion, such that a reception signal of the third communication system is outputted from the third signal input-output portion, and such that a reception signal of the first communication system and a transmission-reception signal of the fourth communication system are inputted to and outputted from the fourth signal input-output portion.

Claim 16 (previously presented): A high-frequency module as claimed in claim 15, wherein a first diplexer connected to the first signal input-output portion and arranged to separate a transmission signal of the first communication system and a reception signal of the second communication system and a second diplexer connected to the fourth signal input-output portion and arranged to separate a reception signal of the first communication system and a transmission-reception signal of the fourth communication system are included.

Claim 17 (currently amended): ~~A high-frequency module as claimed in claim 12,~~
A high-frequency module for transmitting and receiving transmission-reception signals of communication systems of at least three kinds from an antenna, the signals to be inputted and outputted from particular input-output portions, respectively, the high-frequency module comprising:

an FET switch including an antenna input-output portion to be connected to the antenna and at least three signal input-output portions whose connection to the antenna input-output portion is switched in accordance with control signals to be inputted, the FET being constituted such that the transmission signals of communication systems of three kinds are inputted from different signal input-output portions and such that reception signals of at least two communication systems are outputted from the same

signal input-output portion; and

a diplexer connected to the signal input-output portion of the FET switch, from which reception signals of at least two communication systems are outputted, the diplexer being arranged to separate the reception signals of the at least two communication systems; wherein

the high-frequency module is a high-frequency module arranged to transmit and receive transmission-reception signals of first, second, and third communication systems from the antenna, and the FET switch includes first, second third, and fourth signal input-output portions and is constituted such that a transmission signal of the first communication system is inputted to the first signal input-output portion, such that transmission signals of the second communication system and the third communication system are inputted to the second signal input-output portion, such that a reception signal of the third communication system is outputted from the third signal input-output portion, and such that a reception signal of the first communication system and a reception signal of the second communication system are outputted from the fourth signal input-output portion.

Claim 18 (previously presented): A high-frequency module as claimed in claim 17, wherein a diplexer is connected to the fourth signal input-output portion and arranged to separate a reception signal of the first communication system and a reception signal of the second communication system.

Claim 19 (previously presented): A high-frequency module as claimed in claim 12, wherein the FET switch is an FET switch including GaAs.

Claim 20 (previously presented): A high-frequency module as claimed in claim 12, wherein the high-frequency module includes a laminate having dielectric layers laminated therein, and each circuit element constituting the diplexer is made up of an electrode pattern disposed on the surface of the dielectric layer.

Claim 21 (previously presented): A high-frequency module as claimed in claim 20, wherein, on an uppermost surface of the laminate, a plurality of lands for mounting an antenna input-output portion and each signal input-output portion of the FET switch are disposed and a grounding electrode is disposed substantially in the center where the plurality of lands are disposed.

Claim 22 (currently amended): A high-frequency module as claimed in claim 20, wherein, on an lowermost surface of the laminate, a plurality of electrodes for mounting the laminate on a mounting substrate is disposed, and an electrode of the input-output portion for inputting a transmission signal and an electrode of the antenna input-output portion in the plurality of electrodes are disposed along different sides of the laminate.

Claim 23 (previously presented): A high-frequency module as claimed in 20, wherein, on an uppermost surface of the laminate, a plurality of lands for mounting the antenna input-output portion and each of the at least three signal input-output portions of the FET switch are disposed and a grounding electrode is provided inside the laminate at a location corresponding to where the plurality of lands are disposed.

Claim 24 (new): A high-frequency module as claimed in claim 15, wherein the FET switch is an FET switch including GaAs.

Claim 25 (new): A high-frequency module as claimed in claim 15, wherein the high-frequency module includes a laminate having dielectric layers laminated therein, and each circuit element constituting the diplexer is made up of an electrode pattern disposed on the surface of the dielectric layer.

Claim 26 (new): A high-frequency module as claimed in claim 25, wherein, on an uppermost surface of the laminate, a plurality of lands for mounting an antenna input-output portion and each signal input-output portion of the FET switch are disposed and a grounding electrode is disposed substantially in the center where the plurality of lands

are disposed.

Claim 27 (new): A high-frequency module as claimed in claim 25, wherein, on a lowermost surface of the laminate, a plurality of electrodes for mounting the laminate on a mounting substrate is disposed, and an electrode of the input-output portion for inputting a transmission signal and an electrode of the antenna input-output portion in the plurality of electrodes are disposed along different sides of the laminate.

Claim 28 (new): A high-frequency module as claimed in 25, wherein, on an uppermost surface of the laminate, a plurality of lands for mounting the antenna input-output portion and each of the at least three signal input-output portions of the FET switch are disposed and a grounding electrode is provided inside the laminate at a location corresponding to where the plurality of lands are disposed.

Claim 29 (new): A high-frequency module as claimed in claim 17, wherein the FET switch is an FET switch including GaAs.

Claim 30 (new): A high-frequency module as claimed in claim 17, wherein the high-frequency module includes a laminate having dielectric layers laminated therein, and each circuit element constituting the diplexer is made up of an electrode pattern disposed on the surface of the dielectric layer.

Claim 31 (new): A high-frequency module as claimed in claim 30, wherein, on an uppermost surface of the laminate, a plurality of lands for mounting an antenna input-output portion and each signal input-output portion of the FET switch are disposed and a grounding electrode is disposed substantially in the center where the plurality of lands are disposed.

Claim 32 (new): A high-frequency module as claimed in claim 30, wherein, on a lowermost surface of the laminate, a plurality of electrodes for mounting the laminate on

a mounting substrate is disposed, and an electrode of the input-output portion for inputting a transmission signal and an electrode of the antenna input-output portion in the plurality of electrodes are disposed along different sides of the laminate.

Claim 33 (new): A high-frequency module as claimed in 30, wherein, on an uppermost surface of the laminate, a plurality of lands for mounting the antenna input-output portion and each of the at least there signal input-output portions of the FET switch are disposed and a grounding electrode is provided inside the laminate at a location corresponding to where the plurality of lands are disposed.